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# **FDA15N65**

## 650V N-Channel MOSFET

#### **Features**

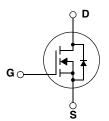
- 16A, 650V,  $R_{DS(on)} = 0.44\Omega @V_{GS} = 10 V$
- Low gate charge (typical 48.5 nC)
- Low C<sub>rss</sub> (typical 23.6 pF)
- · Fast switching
- · 100% avalanche tested
- · Improved dv/dt capability

# **Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies and active power factor correction.





## **Absolute Maximum Ratings**

Symbol	P	arameter		FDA15N65	Unit
V <sub>DSS</sub>	Drain-Source Voltage			650	V
I <sub>D</sub>		Continuous ( $T_C = 25^{\circ}C$ ) Continuous ( $T_C = 100^{\circ}C$ )		16 9.6	A A
I <sub>DM</sub>	Drain Current - F	Pulsed	(Note 1)	64	A
V <sub>GSS</sub>	Gate-Source voltage		± 30	V	
E <sub>AS</sub>	Single Pulsed Avalanche	Energy	(Note 2)	637	mJ
I <sub>AR</sub>	Avalanche Current		(Note 1)	16	Α
E <sub>AR</sub>	Repetitive Avalanche Ene	ergy	(Note 1)	26	mJ
dv/dt	Peak Diode Recovery dv/	/dt	(Note 3)	4.5	V/ns
P <sub>D</sub>		<sub>C</sub> = 25°C) Derate above 25°C		260 2.1	W W/°C
T <sub>J,</sub> T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C	
T <sub>L</sub>	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300	°C	

#### **Thermal Characteristics**

Symbol	Parameter	Min.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.48	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.24		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		40	°C/W

# **Package Marking and Ordering Information**

<b>Device Marking</b>	Device	Package	Reel Size	Tape Width	Quantity
FDA15N65	FDA15N65	TO-3PN		-	30

# Electrical Characteristics T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min	Тур	Max	Units	
Off Characteristics							
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0V$ , $I_D = 250\mu A$ , $T_J = 25^{\circ}C$	650			V	
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, Referenced to 25°C		0.65		V/°C	
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 650V, V <sub>GS</sub> = 0V V <sub>DS</sub> = 520V, T <sub>C</sub> = 125°C			1 10	μ <b>Α</b> μ <b>Α</b>	
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30V, V <sub>DS</sub> = 0V	-		100	nA	
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V$ , $V_{DS} = 0V$			-100	nA	
On Charac	teristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V	
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 8A		0.36	0.44	Ω	
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40V, I <sub>D</sub> = 8A (Note 4)	-	19.2		S	
Dynamic C	: Characteristics				•		
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$		2380	3095	pF	
C <sub>oss</sub>	Output Capacitance	f = 1.0MHz		295	385	pF	
C <sub>rss</sub>	Reverse Transfer Capacitance		1	23.6	35.5	pF	
Switching	Characteristics						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 325V, I <sub>D</sub> = 15A	ı	65	140	ns	
t <sub>r</sub>	Turn-On Rise Time	$R_G = 21.7\Omega$	1	125	260	ns	
$t_{d(off)}$	Turn-Off Delay Time		ı	105	220	ns	
t <sub>f</sub>	Turn-Off Fall Time	(Note 4, 5)		65	140	ns	
$Q_g$	Total Gate Charge	V <sub>DS</sub> = 520V, I <sub>D</sub> = 15A	1	48.5	63.0	nC	
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> = 10V	ı	14.0		nC	
$Q_{gd}$	Gate-Drain Charge	(Note 4, 5)	-	21.2		nC	
Drain-Source Diode Characteristics and Maximum Ratings							
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current				16	Α	
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Fo	orward Current	ı		64	Α	
$V_{SD}$	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 16A	-		1.4	V	
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0V, I <sub>S</sub> = 15A	-	496		ns	
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s $ (Note 4)	-	5.69		μС	

#### NOTES

<sup>1.</sup> Repetitive Rating: Pulse width limited by maximum junction temperature

<sup>2.</sup> L = 4.6mH, I<sub>AS</sub> = 16A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>J</sub> = 25 $^{\circ}$ C

<sup>3.</sup>  $I_{SD} \leq$  16A, di/dt  $\leq$  200A/ $\mu$ s,  $V_{DD} \leq$  BV $_{DSS}$ , Starting  $T_J$  = 25°C

<sup>4.</sup> Pulse Test: Pulse width  $\leq 300 \mu \text{s}, \, \text{Duty Cycle} \leq 2\%$ 

<sup>5.</sup> Essentially Independent of Operating Temperature Typical Characteristics

# **Typical Performance Characteristics**

Figure 1. On-Region Characteristics

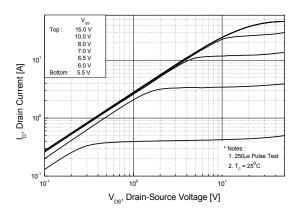


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

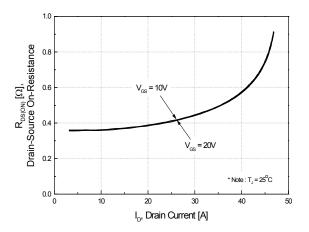


Figure 5. Capacitance Characteristics

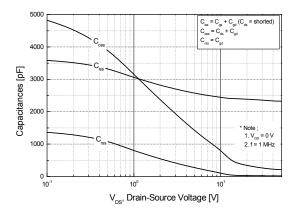


Figure 2. Transfer Characteristics

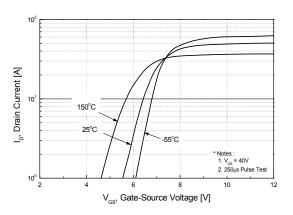


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

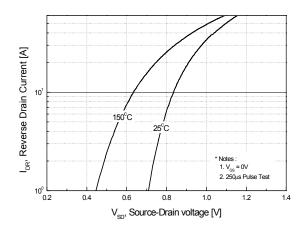
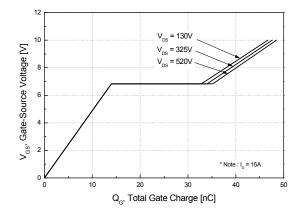


Figure 6. Gate Charge Characteristics



3

# **Typical Performance Characteristics** (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

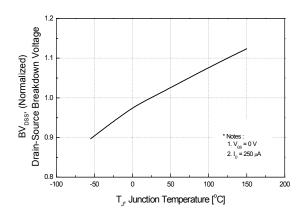


Figure 8. On-Resistance Variation vs. Temperature

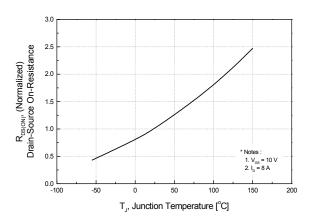


Figure 9. Safe Operating Area

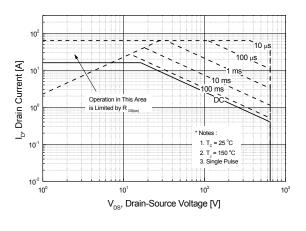


Figure 10. Maximum Drain Current vs. Case Temperature

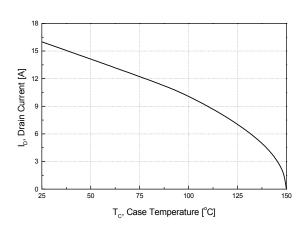
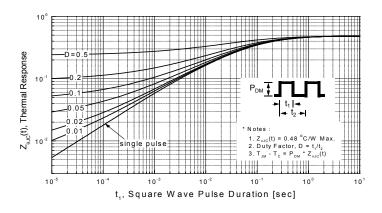
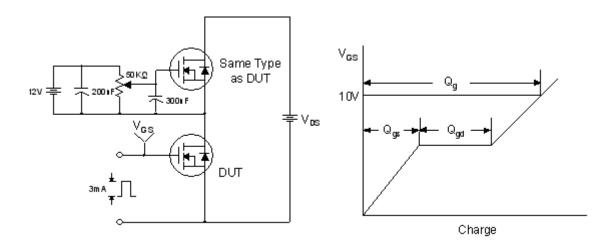


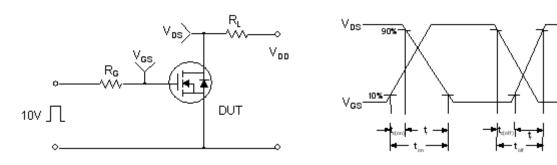
Figure 11. Transient Thermal Response Curve



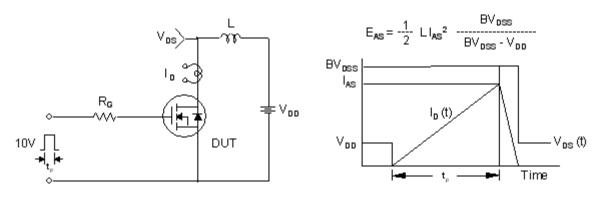
## **Gate Charge Test Circuit & Waveform**



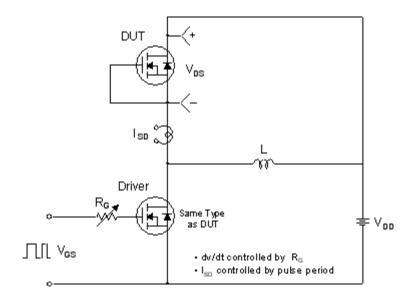
## **Resistive Switching Test Circuit & Waveforms**

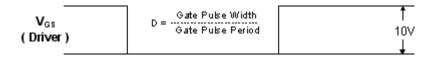


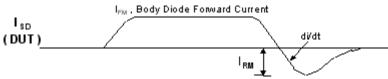
## **Unclamped Inductive Switching Test Circuit & Waveforms**



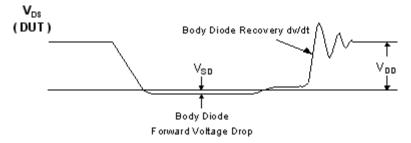
## Peak Diode Recovery dv/dt Test Circuit & Waveforms





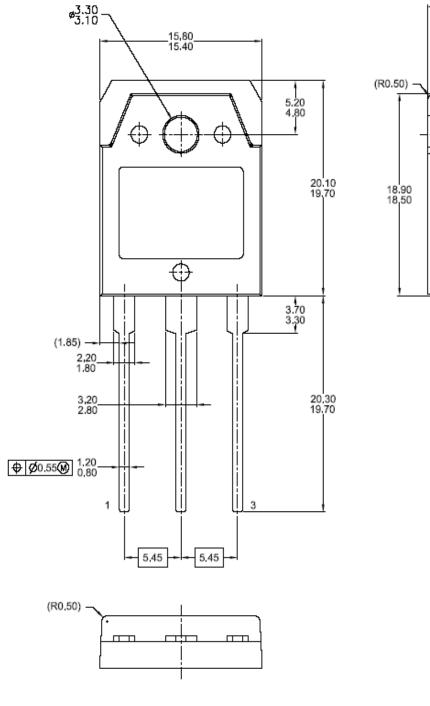


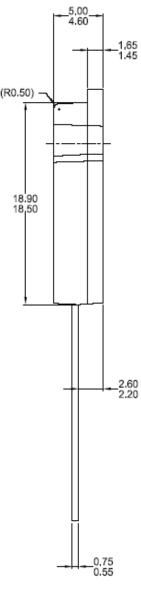
Body Diode Reverse Current



# **Mechanical Dimensions**

# TO-3PN





Dimensions in Millimeters

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Programmable Active Droop™

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UniFET™ VCX™ Wire™

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